

MCS®-51 and MCS®-96 Packaging Information

November 1994

Order Number: 272118-001

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MCS-51 and MCS-96 Packaging Information

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MCS-51 AND MCS-96 PACKAGING INFORMATION

Intel Product Identification Codes

Up to 15 Alphanumeric Characters for Device Types

Up to 6 Alphanumeric Characters to Show Customer Specific Requirements

Package Type

Ceramic Pin Grid Array Ceramic Dual In-Line Package

Cerdip Dual In-Line Package

ΚU Plastic Quad Flatpack Package, Fine Pitch, Die Up

Plastic Leaded Chip Carrier Plastic Dual In-Line Package

Ceramic Leadless Chip Carrier

S Quad Flatpack Package

U - Plastic Dual In-Line Package (Shrink)

Indicates extended operating temperature range (-40° C to $+85^{\circ}$ C) express product with 160 ± 8 hrs. dynamic

Indicates commercial temperature range (0°C to 70°C) express product with 160 ±8 hrs. dynamic burn-in Indicates extended temperature range (-40°C to +85°C) express product without burn-in. Q T

272118-12

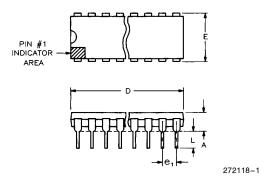
EXAMPLES:

N80C196KR LN87C54

PLCC, 16 MHz, Commercial Temperature Range PLCC, 12 MHz, Extended Temperature Range (Express)



40-LEAD PLASTIC DUAL IN-LINE PACKAGE (TYPE N)

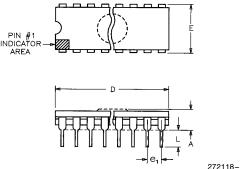


Family: Plastic Dual In-Line Package				
Symbol Millimeters Approx* Inches Approx*				
Α	5	0.2		
D	53	2.1		
E	16	0.6		
e ₁	2.5	0.10		
L	3	0.1		

^{*}For exact dimensions consult the Packaging Handbook (#240800).



40-LEAD CERDIP DUAL IN-LINE PACKAGE (TYPE D)



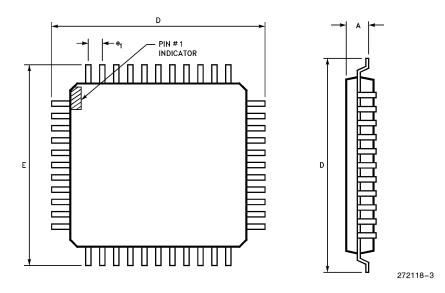
2	27	2	11	8	-	2

Family: Cerdip Dual In-Line Package				
Symbol Millimeters Approx* Inches Approx*				
Α	5.8	0.2		
D	53	2.1		
E	16	0.6		
e ₁	2.5	0.10		
L	3	0.1		

^{*}For exact dimensions consult the Packaging Handbook (#240800).



44-LEAD QUAD FLATPACK PACKAGE (TYPE S) VARIATION: SQUARE

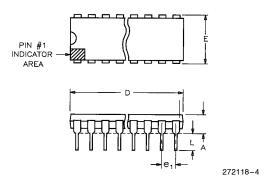


Family: Quad Flatpack Package		
Symbol Millimeters Approx*		
A	3	
D	13	
E	13	
e ₁	0.8	

^{*}For exact dimensions consult the Packaging Handbook (#240800).



48-LEAD PLASTIC DUAL IN-LINE PACKAGE (TYPE N)

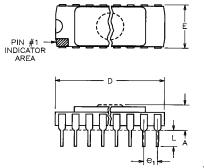


Family: Plastic Dual In-Line Package				
Symbol Millimeters Approx* Inches Approx*				
А	5	0.2		
D	62	2.5		
Е	16	0.6		
e ₁	2.5	0.1		
L	3	0.1		

^{*}For exact dimensions consult the Packaging Handbook (#240800).



48-LEAD CERAMIC DUAL IN-LINE PACKAGE (TYPE C)



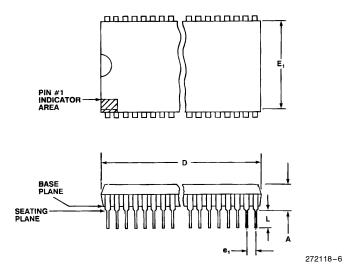
272118-5

Family: Ceramic Side Braze Dual In-Line			
Symbol Millimeters Approx* Inches Approx			
Α	6(1)	0.2(1)	
Α	7(2)	0.3(2)	
D	62	2.5	
E	16	0.6	
e ₁	2.5	0.1	
L	3	0.1	

NOTES: 1. Solid LID 2. EPROM LID

^{*}For exact dimensions consult the Packaging Handbook (#240800).

64-LEAD PLASTIC DUAL IN-LINE PACKAGE (SHRINK) (TYPE U)

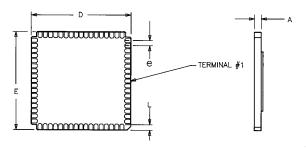


Family: Plastic Dual In-Line Package			
Symbol Millimeters Approx* Inches Approx*			
A	6	0.3	
D	59	2.3	
E ₁	18	0.7	
e ₁	1.8	0.07	
L	3	0.1	

^{*}For exact dimensions consult the Packaging Handbook (#240800).



68-CERAMIC LEADLESS CHIP CARRIER (TYPE R) VARIATION: B



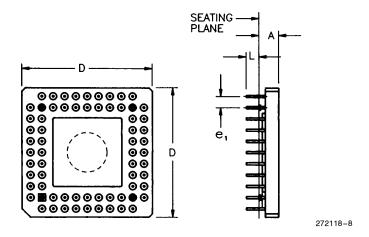
272118-7

Family: Ceramic Leadless Chip Carrier				
Symbol Millimeters Approx* Inches Approx*				
A	3	0.1		
D	25	1.0		
E	25	1.0		
е	1.3	0.05		
L	1	0.1		

^{*}For exact dimensions consult the Packaging Handbook (#240800).



68-LEAD CERAMIC PIN GRID ARRAY PACKAGE (TYPE A)

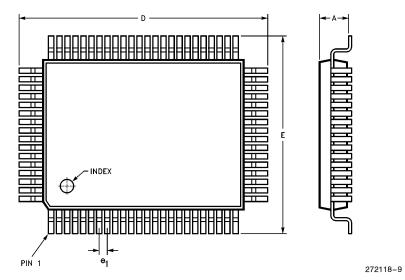


Family: Ceramic Pin Grid Array Package				
Symbol Millimeters Approx* Inches Approx*				
A	5	0.2		
D	30	1.2		
e ₁	2.5	0.1		
L	2	0.1		

^{*}For exact dimensions consult the Packaging Handbook (#240800).



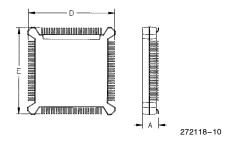
80-LEAD QUAD FLATPACK PACKAGE (TYPE S) VARIATION: RECTANGULAR



Family: Quad Flatpack Package		
Symbol Millimeters Approx*		
A	3	
D	25	
E	19	
e ₁	0.8	

^{*}For exact dimensions consult the Packaging Handbook (#240800).

100-LEAD PLASTIC QUAD FLATPACK PACKAGE (TYPE KU)

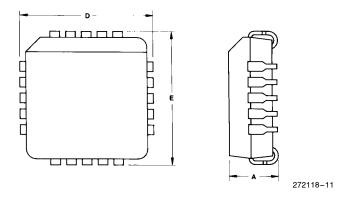


Family: Plastic Quad Flatpack (0.025 Inch (0.635mm) Pitch)				
Symbol Description Inches Approx* Millimeters Approx*				
Α	Package Height	0.2	5	
D, E Terminal Dimension 0.9 23				

^{*}For exact dimensions consult the Packaging Handbook (#240800).



44/52/68/84-LEAD PLASTIC LEADED CHIP CARRIER (TYPE N)



Family: Plastic Leaded Chip Carrier—Square						
Symbol	44-Lead					
	Millimeters Approx*	Inches Approx*				
А	5	0.2				
D	18	0.7				
Е	18	0.7				

Family: Plastic Leaded Chip Carrier—Square							
Symbol	Millimeters Approx*		Inches Approx*				
	68-Lead	52-Lead	84-Lead	68-Lead	52-Lead	84-Lead	
Α	5	5	5	0.2	0.2	0.2	
D	26	21	31	1.0	0.8	1.2	
E	26	21	31	1.0	0.8	1.2	

^{*}For exact dimensions consult the Packaging Handbook (#240800).

